

REMARKS

In the Office Action the Examiner rejected claims 1-6 and 11-18 under 35 U.S.C. 102 as being anticipated and claims 7-9 and 19-20 under 35 U.S.C. 103 as being obvious. Claims 21-30 have been withdrawn. Claims 1-20 have been amended and remain under examination.

The Examiner used Eissa as the anticipating reference and added Avanzino for obviousness. Eissa teaches a chemical mechanical polishing process (CMP) that exposes copper. It is this copper that is protected by applying terizole to the copper to form a compound 120 as shown in FIGs. 2D-2G. This compound 120 is a just a portion of the overall process to provide the desired cleaning of the copper surface after CMP to allow for a subsequent deposition of a dielectric layer. A use of applicants' invention may in fact occur after the last step of removing compound 120 which has the effect of exposing the copper to ambient conditions. Avancino is somewhat similar forming a passivating layer on an exposed copper surface and then removing that passivating layer prior to depositing the next layer. Claims 1 and 13 have been amended to clarify that the removal of the sacrificial layer does not require an additional step from a subsequent deposition process. This of course has the benefit of not requiring an added step for removing the protective layer. Further, for many applications that also has the benefit of providing protection up to the point of entry into the deposition equipment. Other benefits are also highlighted by some of the dependent claims such as being useable on more than one kind of metal, being useful in more than just a CMP situation, being only a monolayer, and being able to be applied in vapor form. Accordingly, applicants submit that these claims are neither anticipated by nor obvious from the references cited by the Examiner.

The amendments to the two paragraphs are to correct minor errors.

Attached are the replacement sheet of drawings and the annotated sheet of drawings showing the change. The numeral 18 is extraneous in FIG. 3.

No amendment made was related to the statutory requirements of patentability unless expressly stated herein. No amendment made was for the purpose of narrowing the scope of any claim, unless Applicant has argued herein that such amendment was made to distinguish over a particular reference or combination of references.


Applicants believe the application is in condition for allowance which action is respectfully solicited. Please contact the below-signed if there are any issues regarding this communication or otherwise concerning the current application.

Respectfully submitted,

SEND CORRESPONDENCE TO:

Freescale Semiconductor, Inc.
Law Department

Customer Number: 23125

By: 
James L. Clingan, Jr.
Attorney of Record
Reg. No.: 30,163
Telephone:
Fax No.: (512) 996-6854

Amendments to the Drawings

The attached sheet of drawings includes a change to FIG. 3. This sheet, which includes FIGs. 3 and 4, replaces the original sheet including FIGs. 3 and 4. In FIG. 3, a previously extraneous numeral has been removed.

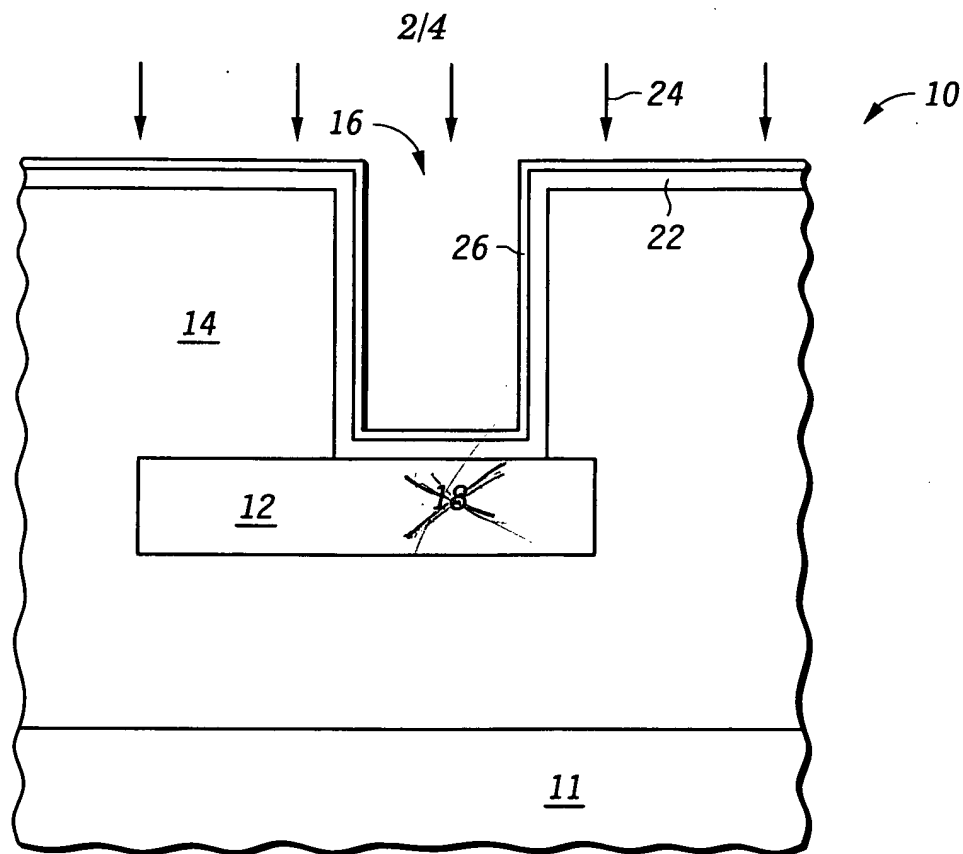


FIG. 3

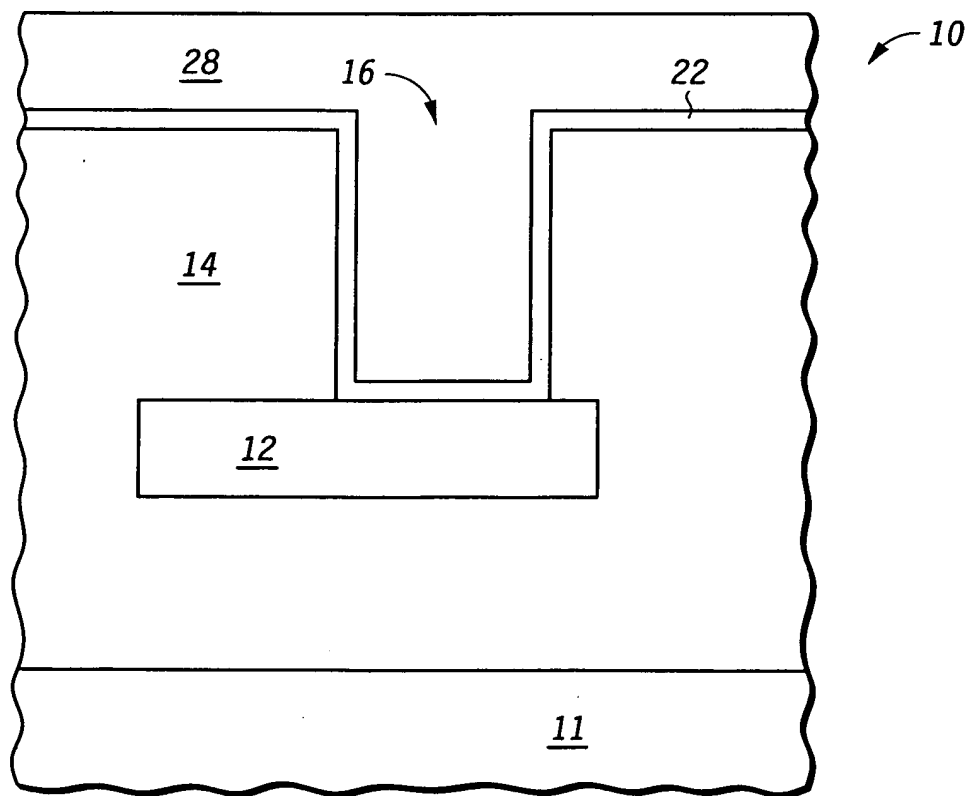


FIG. 4